

Appl. No. 09/731,226
Amdt. dated February 2, 2004
Reply to Office Action of December 30, 2003

PATENT**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1.-9. (canceled)

Claim 10. (previously presented) A chip device comprising:

a non-passivated die;

a first titanium layer on the non-passivated die;

a copper layer directly on the first titanium layer;

a second titanium layer directly on the copper layer, wherein the second titanium layer includes an aperture;

a copper structure within the aperture of the second titanium layer; and

a solder structure over the copper structure.

Claim 11. (previously presented) The chip device of claim 10 wherein the solder structure is a solder ball.

Claim 12. (previously presented) The chip device of claim 10 wherein the first titanium layer, the copper layer, the second titanium layer, the copper structure, and the solder structure are at non-isolation locations of the non-passivated die.